



## Technical Data Sheet

# DOWSIL™ TC-5515 LT Low Density Thermal Conductive Gap Filler Developmental Sample

### Features

- Thermal conductivity 1.50 W/m·k (ASTM D5470)
- Specific gravity 1.91
- Room temperature cure or heat accelerated cure

### Applications

DOWSIL™ TC-5515 LT Low Density Thermally Conductive Gap Filler is a soft and compressible material once cured, designed to dissipate the heat from EV battery or other electronic devices.

### Typical Properties

Specification Writers: These values are not intended for use in preparing specifications.

Property	Unit	Result
One or Two-part	-	Two
Mix ratio (Weight/ Volume)	-	1:1
Color - Part A	-	White
Color - Part B	-	Blue
Viscosity at 10 s <sup>-1</sup> , Part A	Pa·s	138
Viscosity at 10 s <sup>-1</sup> , Part B	Pa·s	83
Viscosity at 10 s <sup>-1</sup> , Mixed	Pa·s	109
Thixotropic index, Mixed (1 s <sup>-1</sup> /10 s <sup>-1</sup> )	-	4.18
Working time at 25 C	Mins	90
Cure Time at 25 C	Mins	360
Specific gravity (Cured)	-	1.91
Durometer	Shore 00	58
Thermal conductivity (ASTM D5470)	W/m·k	1.50
Thermal conductivity (Hot disk)	W/m·k	1.85
Dielectric Strength (fully cured)	kV/mm	16.0
Dielectric Strength (25 C cure 30 mins)	kV/mm	13.3
Volume Resistivity	Ohm·cm	≥ 1.0 E+13
Surface Resistivity	Ohm·cm	≥ 1.0 E+13
Lap shear (Al/PET)	MPa	0.11
Tensile strength	MPa	0.21
Elongation	%	63
UL Flame Classification	-	UL 94 V0

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## Developmental Product Disclaimer

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## DESCRIPTION

DOWSIL™ TC-5515 LT Low Density Thermally Conductive Gap Filler is a soft and compressible material capable to dissipate the heat from the heat source (typically a printed circuit board) to the cold source (typically aluminum housing acting as a heat sink).

This material has been specifically designed to provide reliable cooling performance in automotive electronic modules due to the stability of properties during typical environmental exposure simulating the entire operating life of the module.

DOWSIL™ TC-5515 LT Low Density Thermally Conductive Gap Filler is supplied as a two-part liquid component kits. When the liquid components are thoroughly mixed either by weight or volume, the mixture cures to a soft elastomer. These elastomers cure without exothermal reaction at a constant rate regardless of sectional thickness or degree of confinement.

DOWSIL™ TC-5515 LT Low Density Thermally Conductive Gap Filler require no post-cure and can be placed in service immediately at operating temperatures of -45 to 125°C following the completion of the cure schedule. Thermally conductive silicones function as heat transfer media, with long-term, reliable protection of sensitive circuits, provide a durable dielectric insulation, and are barriers against environmental contaminants and as stress-relieving shock and vibration absorbers over a wide temperature and humidity range.

In addition to sustaining their physical and electrical properties over a broad range of operating conditions, silicones are resistant to ozone and ultraviolet degradation and have good chemical stability. Good heat transfer is dependent on a good interface between the heat producing device and the heat transfer media. Silicones have a low surface tension that enables them to wet most surfaces, which can lower the thermal contact resistance between the substrate and the material.

## HOW TO USE

Two-part materials should be mixed in the proper ratio either by weight or volume. Static Mixer is recommended for manual and automated mixing.

The presence of light-colored streaks or marbling indicates inadequate mixing. Automated airless dispense equipment can be used to reduce or avoid the need to de-air. If de-airing is required to reduce voids in the cured elastomer, consider a vacuum de-air schedule of > 8 inches Hg (or a residual pressure of 10–0 mm of Hg) for 10 minutes or until bubbling subsides.

Although the formulation design of DOWSIL™ TC-5515 LT Low Density Thermally Conductive Gap Filler is made to minimize the risk of filler settlement, upon standing, in rare occasion some filler may settle to the bottom of the liquid after several weeks. Should that be the case, in order to ensure a uniform product mix, the material in each container should be thoroughly mixed prior to use.



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**PROCESSING/  
CURING**

Addition-cure materials can be cured at room temperature or with heat. The cure rate is rapidly accelerated with heat (see cure times in Typical Properties table). Cure progresses evenly throughout the material.

Addition-curing materials contain all the ingredients needed for cure with no by-products from the cure mechanism. Deep-section or confined cures are possible.

**POT LIFE AND  
CURE RATE**

Cure reaction begins with the mixing process. Initially, cure is evidenced by a gradual increase in viscosity, followed by gelation and conversion to its final state. Cure reaction begins with the mixing process. Initially, cure is evidenced by a gradual increase in viscosity, followed by gelation and conversion to its final state. Working time is defined as the time required for viscosity to double after Parts A and B are mixed.

**USEFUL  
TEMPERATURE  
RANGES**

For most uses, DOWSIL™ TC-5515 LT Low Density Thermally Conductive Gap Filler should be operational over a temperature range of -45 to 125°C for long periods of time. However, at both the low and high temperature ends of the spectrum, behavior of the materials and performance in particular applications can become more complex and require additional considerations.

For low-temperature performance, thermal cycling to conditions such as -55°C (-67°F) may be possible, but performance should be verified for your parts or assemblies. Factors that may influence performance are configuration and stress sensitivity of components, cooling rates and hold times, and prior temperature history.

At the high-temperature end, the durability of the cured silicone elastomer is time and temperature dependent. As expected, the higher the temperature, the shorter the time the material will remain useable.

**USABLE LIFE AND  
STORAGE**

Shelf life is indicated by the “Use By” date found on the product label. Any special storage and handling instructions will be printed on the product containers.

For best results, DOWSIL™ TC-5515 LT Thermally Conductive Gap Filler should be stored at or below the maximum specified storage temperature. Special precautions must be taken to prevent moisture from contacting these materials.

Containers should be kept tightly closed and head or air space minimized. Partially filled containers should be purged with dry air or other gases, such as nitrogen. Any special storage and handling instructions will be printed on the product containers.

**PACKAGING  
INFORMATION**

Multiple packaging sizes are available for this product. Please contact your local distributor or Dow.

**LIMITATIONS**

This product is neither tested nor represented as suitable for medical or pharmaceutical uses.

**HEALTH AND  
ENVIRONMENTAL  
INFORMATION**

To support customers in their product safety needs, Dow has an extensive Product Stewardship organization and a team of product safety and regulatory compliance specialists available in each area.

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PRECAUTIONS**

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